L	Hits	Search Text	DB	Time stamp
Number				
1	0	microcircuit and package and stacking and	USPAT;	2002/08/06
		pretested adj circuit	US-PGPUB;	10:51
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
2	0	package and stacking and pretested adj	USPAT;	2002/08/06
		circuit	US-PGPUB;	10:52
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	0	package and pretested adj circuit	USPAT;	2002/08/06
			US-PGPUB;	10:52
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	2	pretested adj circuit	USPAT;	2002/08/06
			US-PGPUB;	10:54
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	5	pretested and microcircuit	USPAT;	2002/08/06
			US-PGPUB;	10:57
			EPO; JPO;	-
			DERWENT;	
			IBM_TDB	
6	19	pre-tested and circuit and 29/\$.ccls.	USPAT;	2002/08/06
			US-PGPUB;	10:58
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

L Number	Hits	Search Text	DB	Time stamp
1	43	circuit adj board and encapsulated and	USPAT;	2002/08/06
		grinding and stacking	US-PGPUB;	08:22
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	34	IC and encapsulated and grinding and	USPAT:	2002/08/06
		stacking	US-PGPUB;	08:35
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	0	20020100600.URPN.	USPAT	2002/08/06
				08:26
4	1	microcircuit and encapsulated and grinding	USPAT;	2002/08/06
	_	and stacking	US-PGPUB;	08:35
			EPO; JPO;	
		*	DERWENT;	
			IBM_TDB	
5	66	circuit and encapsulated and grinding and	USPAT;	2002/08/06
		stacking	US-PGPUB;	08:39
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	5	("3370203" "3577037" "4151543"	USPAT	2002/08/06
		"4363076" "4398235").PN.		08:37
9	9	circuit and encapsulated and grinding and	USPAT;	2002/08/06
	[polishing and stacking	US-PGPUB;	08:40
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	8	BGA and encapsulated and grinding and	USPAT;	2002/08/06
		stacking	US-PGPUB;	08:42
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
11	3	("5304534" "5373627" "5847445").PN.	USPAT	2002/08/06
				08:41
12	13	encapsulated and grinding and stacking and	USPAT;	2002/08/06
		29/\$.ccls.	US-PGPUB;	08:44
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
13	1	chip and encapsulated near grinding and	USPAT;	2002/08/06
		stacking	US-PGPUB;	08:45
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	1	encapsulated near grinding and stacking	USPAT;	2002/08/06
			US-PGPUB;	08:47
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

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			T	
15	0	20010055856.URPN.	USPAT	2002/08/06 08:46
40	7	avinding and stocking and 420/400 calc	HCDAT.	
16	'	grinding and stacking and 438/460.ccls.	USPAT; US-PGPUB;	2002/08/06 08:55
			1	00:55
			EPO; JPO;	
			DERWENT;	
47	4	avinding and stacking and 420/462 and	IBM_TDB	2002/08/06
17	*	grinding and stacking and 438/462.ccls.	USPAT;	08:55
			US-PGPUB; EPO; JPO;	00:55
			1 -	
			DERWENT; IBM_TDB	
18	2	grinding and stacking and 438/465.ccls.	USPAT;	2002/08/06
10	_	grinding and stacking and 430/403.ccis.	US-PGPUB;	08:57
				00:57
			EPO; JPO;	
			DERWENT;	
19	1	"5646067".PN.	IBM_TDB USPAT	2002/08/06
19		5070007 IF ITI	USFAI	08:56
20	0	20010055856.URPN.	USPAT	2002/08/06
20	"	200 10000000 OVE M	JUFAI	08:57
21	178	grinding and stacking and 29/\$.ccls.	USPAT;	2002/08/06
	''	grinding and stacking and 25/4/ccis.	US-PGPUB;	09:25
			EPO; JPO;	03.23
			DERWENT;	
			IBM_TDB	
22	6	("4750090" "5657537" "5699234"	USPAT	2002/08/06
		"5739578" "5844168" "6290540").PN.	00.7.	08:59
23	14	("4237522" "4254446" "4783695"	USPAT	2002/08/06
		"4835704" "4894115" "4933042"		09:01
		"5019946" "5111278" "5161093"		
		"5279029" "5285571" "5347928"		
		"5466634" "5502667").PN.		
24	40		USPAT	2002/08/06
		"3070729" "3139559" "3152288"		09:06
		"3370203" "3746934" "3748479"		
		"4520427" "4525921" "4551629"		
		"4612083" "4638348" "4646128"		
		"4706166" "4727410" "4764846"		
		"4801992" "4818728" "4833568"		
		"4862249" "4868712" "4879258"		
		"4894706" "4901136" "4902641"		
		"4926241" "4956746" "4983533"		
		"5016138" "5019943" "5019946"		
		"5051865" "5064771" "5071792"		
		"5091331" "5162254" "5266833"		
		"5347428").PN.		
25	9	grinding and stacking and (albert et al).in.	USPAT;	2002/08/06
			US-PGPUB;	09:27
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

	2	5086018.pn.	USPAT;	2002/08/05
	_		US-PGPUB;	14:59
			EPO; JPO;	1-100
			DERWENT;	
			IBM_TDB	
-	2	6342398.pn.	USPAT;	2002/08/05
	_	,	US-PGPUB;	13:45
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			DERWENT;	
			IBM_TDB	
_	2	6060373.pn.	USPAT;	2002/08/05
		•	US-PGPUB;	13:45
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3	5454160.pn.	USPAT;	2002/08/05
		•	US-PGPUB;	13:45
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
 -	7	microcircuit and package and stacking and	USPAT;	2002/08/05
		29/\$.ccls.	US-PGPUB;	13:59
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	71	5086018.URPN.	USPAT	2002/08/05
				14:53
-	36	("4862245" "4937656" "4949161"	USPAT	2002/08/05
		"5086018" "5147815" "5218168"		14:56
		"5234866" "5250840" "5256598"		
		"5303120" "5327009" "5331200"		
		"5334873" "5357139" "5360992"		
		"5365113" "5381036" "5384488"		
		"5434106" "5438478" "5508565"		
		"5521426" "5523617" "5528075"		
		"5530292" "5563443" "5585667"		
		"5585668" "5612259" "5637915"		
		"5696665" "5751057" "5780925"		
		"5804870" "5811875" "6066515").PN.		

•	84	("3246386" "3290559" "3313986"	USPAT	2002/08/05
		"3377516" "3403300" "3515949"		14:57
		"3535595" "3614541" "3671812"		
		"3746934" "3949274" "3959579"		
		"4017963" "4116518" "4116519"		
		"4288808" "4288841" "4364620"		
		"4371912" "4379259" "4394712"		
	Ì	"4398235" "4571663" "4574331"		
		"4631573" "4638348" "4638406"		
		"4642735" "4688864" "4696525"		
		"4698663" "4706166" "4761681"		
		"4770640" "4821007" "4841355"		
		"4868712" "4884237" "4924352"		
		"4953005" "4956694" "4996583"		
		"4996587" "5016138" "5025307"		
		"5031072" "5041395" "5043794"		
		"5058265" "5086018" "5107328"		
		"5128831" "5140745" "5155068"		
		"5198888" "5222014" "5231304"		
		"5239447" "5241454" "5281852"		
		"5311401" "5313096" "5343075"		
		"5343366" "5369058" "5373189"		
		"5384689" "5397916" "5420751"		
		"5426566" "5446313" "5479318"		
		"5481133" "5493476" "5499160"		
		"5514907" "5552963" "5561591"		
		"5566051" "5586009" "5605592"		
		"5612570" "5615475" "5723903").PN.		
-	14	("3746934" "4398235" "4521828"	USPAT	2002/08/05
		"4763188" "4796078" "4884237"		14:58
	ļ	"4953060" "4956694" "5151559"		
		"5221642" "5270492" "5279029"		
		"5367766" "5394010").PN.		
_	4	29/841.ccls. and IC and stacking	USPAT;	2002/08/05
	_	20/04 Hoold and 10 and oldoking	US-PGPUB;	15:02
			EPO; JPO;	13.02
			DERWENT;	
			IBM_TDB	
_	0	29/841.ccls. and "PEM" and stacking	USPAT;	2002/08/05
-		LOOT ILCOS. AND FEW AND STACKING	US-PGPUB;	15:02
				13:02
			EPO; JPO;	
			DERWENT;	
	_	00/044	IBM_TDB	
-	0	29/841.ccls. and "PEM"	USPAT;	2002/08/05
			US-PGPUB;	15:02
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	29/841.ccls. and "Plastic encapsulant	USPAT;	2002/08/05
		microcircuit"	US-PGPUB;	15:03
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

	•	UDI41	HCDAT.	2002/09/05
-	0	"Plastic encapsulant microcircuit"	USPAT;	2002/08/05
			US-PGPUB;	15:03
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	"plastic encapsulant microcircuit"	USPAT;	2002/08/05
			US-PGPUB;	15:04
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	plastic same encapsulant near microcircuit	USPAT;	2002/08/05
			US-PGPUB;	15:04
i			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	14	plastic same encapsulant near circuit	USPAT;	2002/08/05
		-	US-PGPUB;	15:05
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	encapsulant near circuit and stacking	USPAT;	2002/08/05
	_		US-PGPUB;	15:06
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
i _	263	encapsulant and circuit and stacking	USPAT;	2002/08/05
-	203	encapsulant and circuit and stacking	US-PGPUB;	15:06
			EPO; JPO;	15:00
			DERWENT;	
	31	anappellant and siverit and stacking and	IBM_TDB	2002/08/05
-	31	encapsulant and circuit and stacking and	USPAT;	
		174/\$.ccls.	US-PGPUB;	15:07
			EPO; JPO;	
			DERWENT;	
	4.5		IBM_TDB	0000/00/00
-	13	encapsulant and circuit and stacking and	USPAT;	2002/08/05
		439/\$.ccls.	US-PGPUB;	15:08
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	10	encapsulant and circuit and stacking and	USPAT;	2002/08/05
		228/\$.ccls.	US-PGPUB;	15:08
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	134	encapsulant and circuit and stacking and	USPAT;	2002/08/05
		257/\$.ccls.	US-PGPUB;	15:09
			EPO; JPO;	
ı			DERWENT;	